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Applicant: Hubert DE STEUR et al.	Case No.: 32860-000291/US
Serial No.: 10/079,896	Filing Date: December 27, 2001
Title: METHOD AND APPARATUS FOR STRUCTURING PRINTED CIRCUIT BOARDS	
Please acknowledge receipt of: Letter Claiming Priority, Priority document Number 110 27 357.6	
By stamping and returning to Harness, Dickey & Pierce, P.L.C.	
Due: N/A	Attorney: DJD - May 20, 2002
<u>USPTO Date Stamp</u>	



(6)

USPTO Date Stamp



PATENT
32860-000291/US

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Hubert DE STEUR et al.

Application No.: 10/076,896

Filed: December 27, 2001

For: METHOD AND APPARATUS FOR STRUCTURING PRINTED CIRCUIT BOARDS

PRIORITY LETTER

May 20, 2002

Honorable Commissioner of Patents and Trademarks
Washington, DC 20231

Dear Sirs:

Pursuant to the provisions of 35 U.S.C. 119, enclosed is/are a certified copy of the following priority document(s).

<u>Application No.</u>	<u>Date Filed</u>	<u>Country</u>
101 27 357.6	6 June 2001	Germany

In support of Applicant's priority claim, please enter this document into the file.

Respectfully submitted,

HARNESS, DICKEY, & PIERCE, P.L.C.

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DJD:kmh

BUNDESREPUBLIK DEUTSCHLAND



"Method and Apparatus
for Structuring Printed
Circuit Boards."
10/079, 896

Prioritätsbescheinigung über die Einreichung einer Patentanmeldung

Aktenzeichen: 101 27 357.6

Anmeldetag: 6. Juni 2001

Anmelder/Inhaber: Siemens Dematic AG, Nürnberg/DE

Bezeichnung: Verfahren und Einrichtung zur Strukturierung
von Leiterplatten

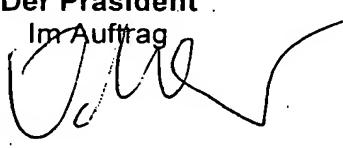
IPC: H 05 K 3/02

Die angehefteten Stücke sind eine richtige und genaue Wiedergabe der
ursprünglichen Unterlagen dieser Patentanmeldung.

München, den 4. März 2002
Deutsches Patent- und Markenamt

Der Präsident

Im Auftrag


Walther